



Shenzhen Tuofeng Semiconductor Technology Co., Ltd

P -CHANNEL ENHANCEMENT MODE POWER MOSFET**TF030P02K****• General Description**

The TF030P02K combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

Advance high cell density Trench technology

Low $R_{DS(ON)}$ to minimize conductive loss

Low Gate Charge for fast switching

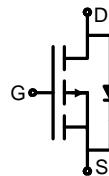
Low Thermal resistance

• Application

Load Switches

DC/DC

BLDC Motor driver

• Product Summary $V_{DS} = -20V$ $I_D = -120A$ $R_{DS(on)(-4.5V\ typ)} = 2.2m\Omega$ $R_{DS(on)(-2.5V\ typ)} = 2.9m\Omega$ **TO-251****TO-252****• Ordering Information:**

Part NO.	TF030P02K
Marking1	030P02K:TF030P02K
Marking2	Logo:tuofeng; Y:year code; XX:Week; AA:device code;
Basic ordering unit (pcs)	2500

• Absolute Maximum Ratings ($T_c = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	$I_{D@TC=25^\circ C}$	-120	A
	$I_{D@TC=75^\circ C}$	-86	A
	$I_{D@TC=100^\circ C}$	-72	A
Pulsed Drain Current ^①	I_{DM}	-350	A
Total Power Dissipation ^②	P_D	50	W
Total Power Dissipation($TA=25^\circ C$)	$P_{D@TA=25^\circ C}$	2.0	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ C$
Storage Temperature	T_{STG}	-55 to 150	$^\circ C$
Single Pulse Avalanche Energy @ $L=0.5mH$	E_{AS}	150	mJ
Avalanche Current @ $L=0.5mH$	I_{AS}	-24.8	A



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P -CHANNEL ENHANCEMENT MODE POWER MOSFET**TF030P02K****Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D = -250\mu\text{A}$	-20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -20\text{V}$, $V_{GS}=0\text{V}$,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS} = \pm 12\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D = -250\mu\text{A}$	-0.4	-	-1.0	V
$R_{DS(\text{on})}$	Static Drain-Source on-Resistance note2	$V_{GS} = -4.5\text{V}$, $I_D = -30\text{A}$	-	2.2	2.7	$\text{m}\Omega$
		$V_{GS} = -2.5\text{V}$, $I_D = -20\text{A}$	-	2.9	3.8	
		$V_{GS} = -1.8\text{V}$, $I_D = -15\text{A}$	-	3.9	5.7	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = -10\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	15	-	nF
C_{oss}	Output Capacitance		-	1600	-	pF
C_{rss}	Reverse Transfer Capacitance		-	1068	-	pF
Q_g	Total Gate Charge	$V_{DS} = -10\text{V}$, $I_D = -20\text{A}$, $V_{GS} = -4.5\text{V}$	-	100	-	nC
Q_{gs}	Gate-Source Charge		-	21	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	32	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -10\text{V}$, $R_L=0.5\Omega$, $V_{GS} = -4.5\text{V}$, $R_{\text{GEN}}=3\Omega$	-	20	-	ns
t_r	Turn-on Rise Time		-	50	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	100	-	ns
t_f	Turn-off Fall Time		-	40	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	-85	A	
I_{sM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-350	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s = -30\text{A}$	-	-0.8	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2.EAS condition: $T_J=25^\circ\text{C}$, $V_{DD}=-10\text{V}$, $V_G=-10\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_{AS}=-24.8\text{A}$ 3.Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

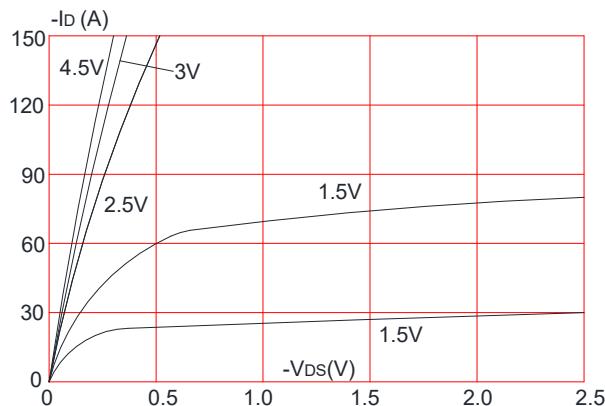


Figure 2: Typical Transfer Characteristics

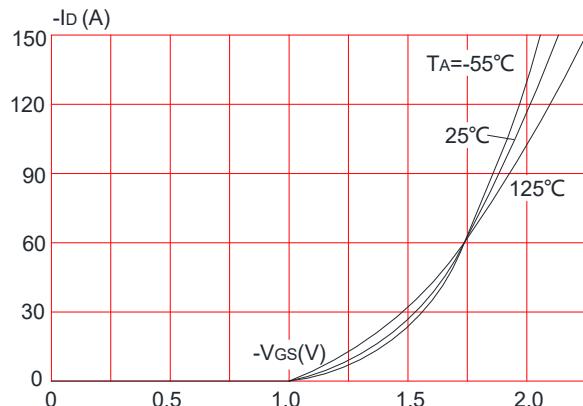


Figure 3: On-resistance vs. Drain Current

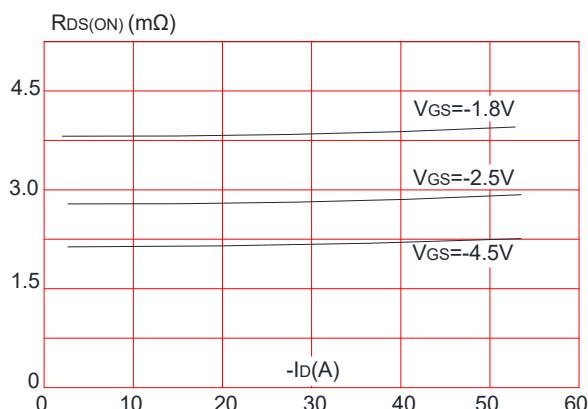


Figure 4: Body Diode Characteristics

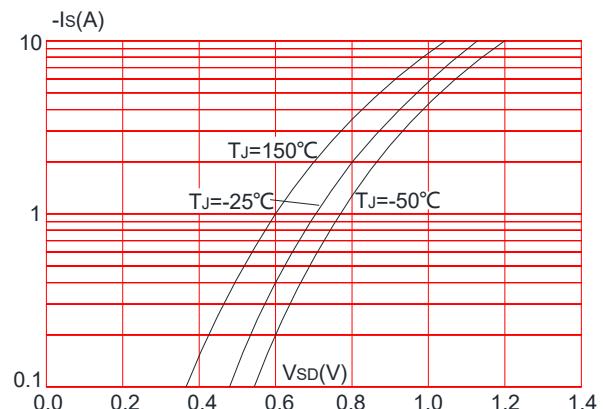


Figure 5: Gate Charge Characteristics

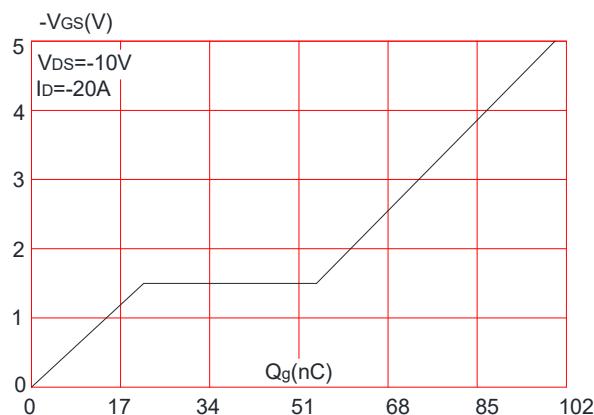


Figure 6: Capacitance Characteristics

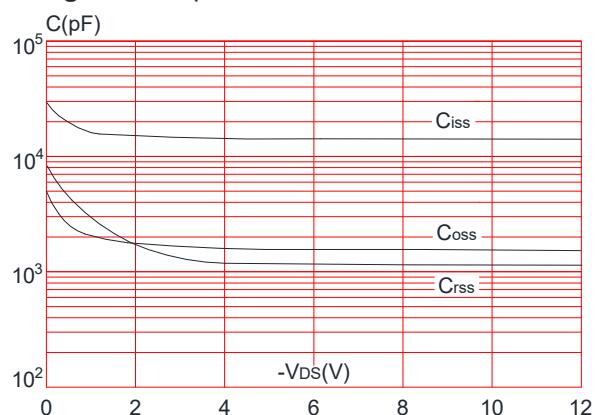


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

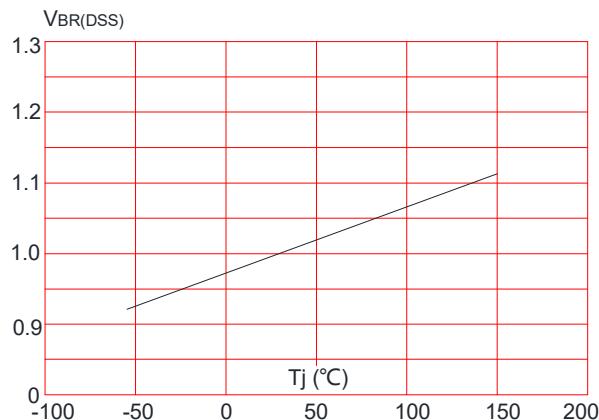


Figure 8: Normalized on Resistance vs. Junction Temperature

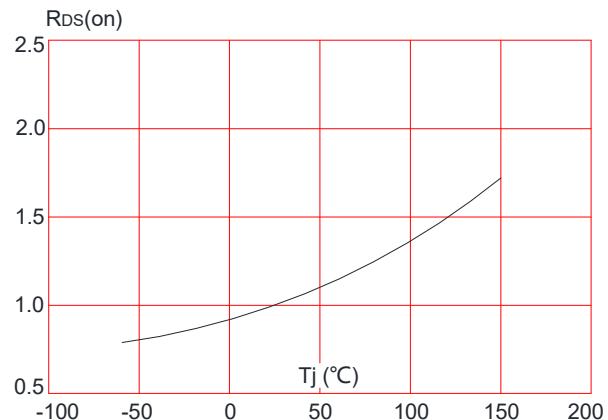


Figure 9: Maximum Safe Operating Area

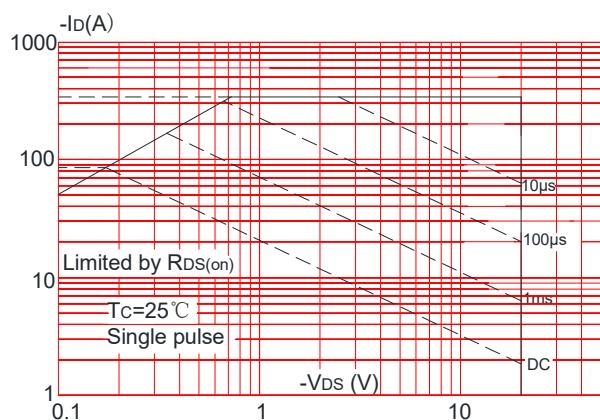


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

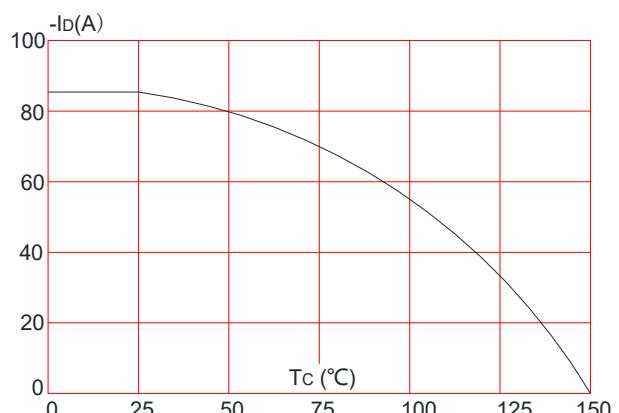
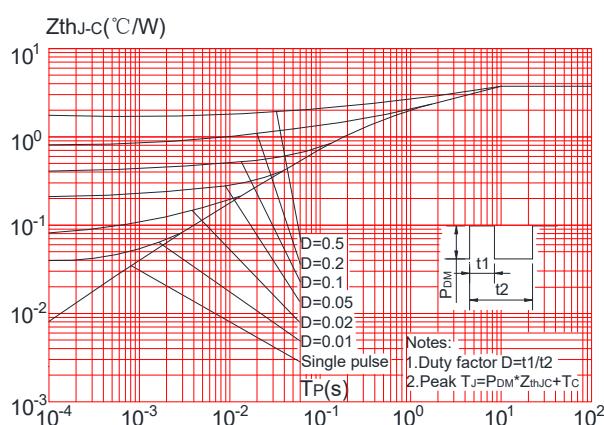
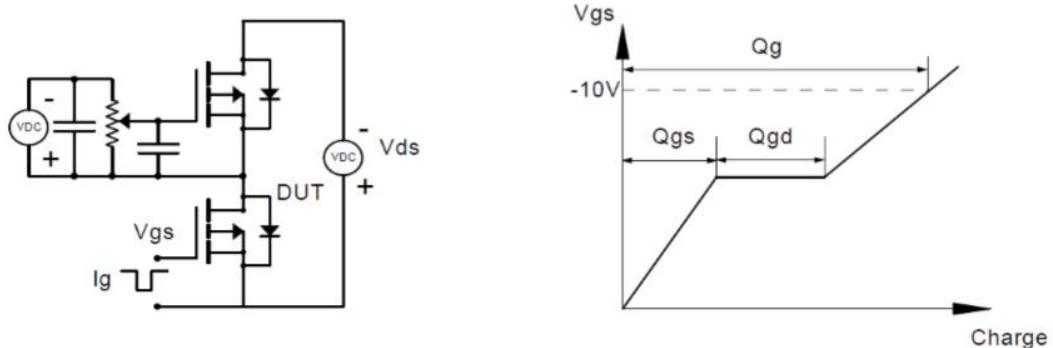


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

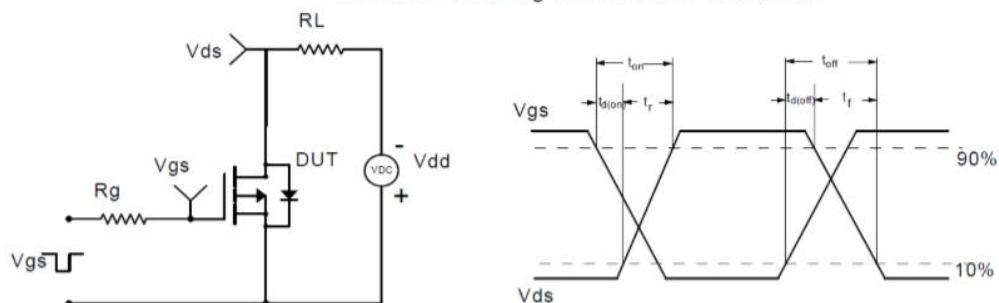


Test Circuit

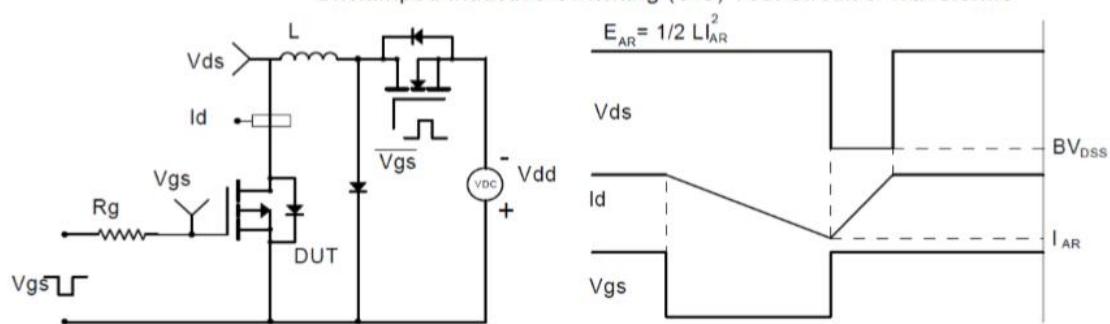
Gate Charge Test Circuit & Waveform



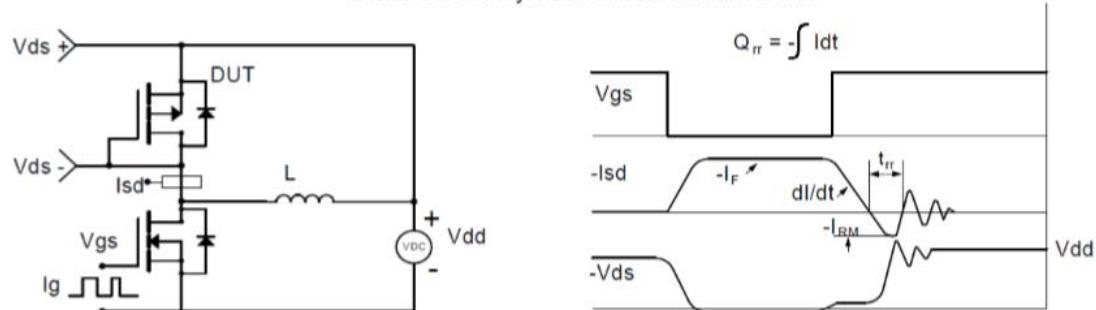
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms





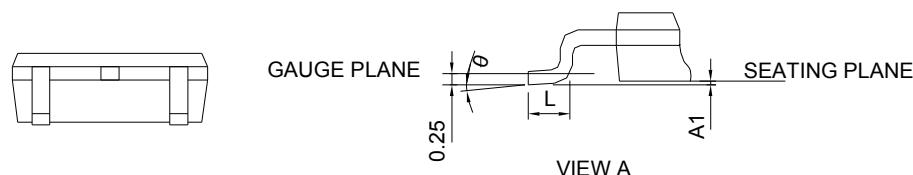
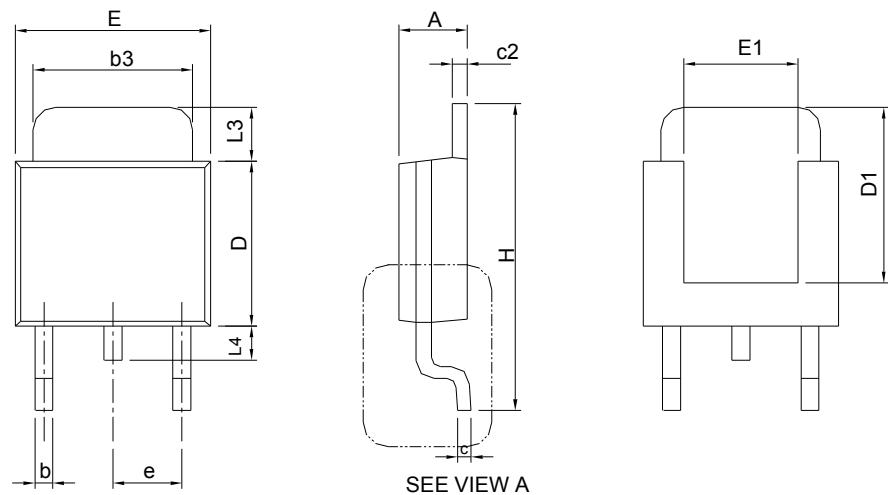
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TF030P02K

Package Information

TO-252



SYMBOL	TO-252			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.39	0.086	0.094
A1		0.13		0.005
b	0.50	0.89	0.020	0.035
b3	4.95	5.46	0.195	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.89	0.018	0.035
D	5.33	6.22	0.210	0.245
D1	4.57	6.00	0.180	0.236
E	6.35	6.73	0.250	0.265
E1	3.81	6.00	0.150	0.236
e	2.29 BSC		0.090 BSC	
H	9.40	10.41	0.370	0.410
L	0.90	1.78	0.035	0.070
L3	0.89	2.03	0.035	0.080
L4		1.02		0.040
θ	0°	8°	0°	8°

RECOMMENDED LAND PATTERN

